IEC 62421

Edition 1.0 2007-08

INTERNATIONAL STANDARD

Electronics assembly technology – Electronic modules

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

PRICE CODE **P**

ICS 31.190

ISBN 2-8318-9300-3

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FOREWORD

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International Standard IEC 62421 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/689/FDIS	91/722/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

ELECTRONICS ASSEMBLY TECHNOLOGY – ELECTRONIC MODULES

1 Scope and object

This International Standard provides a generic standard of electronic modules on which their sectional standards are based.

This standard provides a definition, business model, interface between the trading partners, and related areas of standardization of electronic modules. In addition a generic set of test method is provided.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068 (all parts), *Environmental testing*

IEC 60068-1:1988, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-1: *Environmental Testing – Part 2-1: Tests – Test A: Cold*

IEC 60068-2-2: *Environmental testing – Part 2-2: Tests – Tests B: Dry heat*

IEC 60068-2-6: *Environmental testing – Part 2-6: Tests – Test Fc: Vibration (sinusoidal)*

IEC 60068-2-14: *Environmental testing – Part 2-14: Tests – Test N: Change of temperature*

IEC 60068-2-20: *Environmental testing – Part 2-20: Tests – Test T: Soldering*

IEC 60068-2-21: *Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices*

IEC 60068-2-27: *Environmental testing – Part 2-27: Tests – Test Ea and guidance: Shock*

IEC 60068-2-45: *Environmental testing – Part 2-45: Tests – Test XA and guidance: Immersion in cleaning solvents*

IEC 60068-2-58: *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60068-2-78: *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

ISO 3: *Preferred numbers – Series of preferred numbers*